Standardized Information for Process/Product Change Notification (PCN)

	1. PCN basic data		
1.1 Company TAIWAN SEMICONDUCTOR	TAIWAN SEMICONDUCTOR CO.,LTD		
1.2 PCN No.	PCN20007		
1.3 Title of PCN	Change Molding Compound of Plastic MELF Package to Halogen-Free Version	,	
1.4 Product Category	Active Components - Integrated Circuits	•	
1.5 Issue date	2020/05/27		
1.6 PCN revision history (optional)	1.7 Issue date of previous revision (optional) revision (optional)		

2. PCN Team								
2.1 Contact supplier								
2.1.1 Name	Sunnie Lin							
2.1.2 Phone	+886-2-8913-1588 Ext:2205							
2.1.3 Email	sunnie.lin@mail.ts.com.tw	sunnie.lin@mail.ts.com.tw						
2.2 Team supplier (optional)								
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)						
Chris Lin	+886-2-8913-1588 Ext.: 2406	chris_lin@mail.ts.com.tw						

	3. Changes							
No.	3.0 Ident	3.1 Category	3.2 Type of change					
#1	SEM-PA-11	PROCESS - ASSEMBLY	Change of mold compound / encapsulation material					

	4. Description of change			
	Old	New		
Change #1	Molding Compound for Non-Halogen-Free	Change Molding Compound to Halogen-Free		
4.1 Anticipated impact on form, fit, function, reliability or processability?	Not impact the form, fit, function, reliability or processabili	ity		
4.2 Reference parts with customer number (optional)				

5. Reason / motivation for change					
5.1 Motivation Change Molding Compound of Plastic MELF Package to Halogen-Free Version					
5.2 Additional explanation (optional)					

6. Marking of parts / traceability of change				
6.1 Description	Use data code to traceability			

	7. Timing / schedule						
7.1 Date of qualification results	2020/03/20						
7.2 Last order date (optional)	2020/11/25						
7.3 Last delivery date (optional)	2021/11/25						
7.4 Intended start of delivery	2020/08/27						
7.5 Qualification samples available?	When get customer order a	nd after 2 weeks can be submitted					
7.6 Customer feedback required until	2020/07/13						

8. Qualification / validation							
8.1 Description (e.g. qual. plan/report, AEC-Q) According to JESD22							
8.2 Qualification report and qualification results	available (see attachement)	issue date	2020/03/20				

9. Input to customer for risk assessment process

Human Resource : No Risk Equipment : No Risk Technique-Wafer : No Risk Technique-Assembly : No Risk Form/ Fit / Function : No Risk Reliability : No Risk

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)

Refer to the official e-mail announcement for the applicable documents.

	11. Affected parts								
11.1 Current							11.2 New (if	applicable)	
11.1.1 Customer Part No.	11.1.2 Supplier Part Name	11.1.3 Supplier Part No. (optional)	11.1.4 Package Name	11.1.5 Part Description (optional)	11.1.6 Additional Part Information (optional)	11.2.2 Supplier Part Name	Supplier Part	11.2.4 Package Name	11.2.6 Additional Part Information (optional)

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